

N-channel TrenchMOS SiliconMAX standard level FET Rev. 02 — 16 December 2010 Product de

Product data sheet

#### **Product profile** 1.

### **1.1 General description**

SiliconMAX standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product is designed and qualified for use in computing, communications, consumer and industrial applications only.

### 1.2 Features and benefits

- Higher operating power due to low thermal resistance
- Low conduction losses due to low on-state resistance
- Suitable for high frequency applications due to fast switching characteristics

### 1.3 Applications

DC-to-DC converters

Switched-mode power supplies

### 1.4 Quick reference data

Table 1.	Quick reference data					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C	-	-	150	V
I <sub>D</sub>	drain current	T <sub>mb</sub> = 25 °C	-	-	55.5	А
P <sub>tot</sub>	total power dissipation		-	-	250	W
Static cha	aracteristics					
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = 10 V; I <sub>D</sub> = 25 A; T <sub>j</sub> = 25 °C	-	24	30	mΩ
Dynamic	characteristics					
$Q_{GD}$	gate-drain charge	V <sub>GS</sub> = 10 V; I <sub>D</sub> = 55.5 A; V <sub>DS</sub> = 120 V; T <sub>j</sub> = 25 °C	-	38	50	nC

# nexperia

### N-channel TrenchMOS SiliconMAX standard level FET

### 2. Pinning information

Table 2.	Pinning	j information		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		-
2	D	drain	mb	
3	S	source		
mb	D	mounting base; connected to drain		mbb076 S

SOT78 (TO-220AB)

### 3. Ordering information

#### Table 3.Ordering information

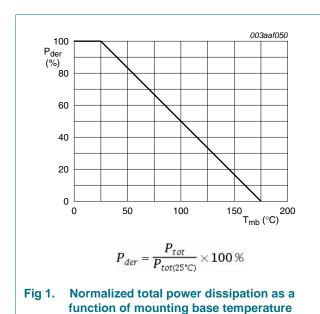
Type number	Package		
	Name	Description	Version
PSMN030-150P	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

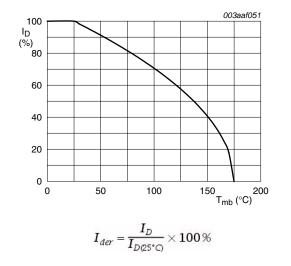
### 4. Limiting values

#### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> ≥ 25 °C; T <sub>j</sub> ≤ 175 °C	-	150	V
V <sub>DGR</sub>	drain-gate voltage	$T_j \ge 25 \text{ °C}; T_j \le 175 \text{ °C}; R_{GS} = 20 \text{ k}\Omega$	-	150	V
V <sub>GS</sub>	gate-source voltage		-20	20	V
I <sub>D</sub>	drain current	T <sub>mb</sub> = 100 °C	-	39	А
		T <sub>mb</sub> = 25 °C	-	55.5	А
I <sub>DM</sub>	peak drain current	pulsed; T <sub>mb</sub> = 25 °C	-	222	А
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C	-	250	W
T <sub>stg</sub>	storage temperature		-55	175	°C
Tj	junction temperature		-55	175	°C
Source-drain	diode				
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	-	55.5	А
I <sub>SM</sub>	peak source current	pulsed; T <sub>mb</sub> = 25 °C	-	222	А
Avalanche ru	Iggedness				
E <sub>DS(AL)S</sub>	non-repetitive drain-source avalanche energy		-	300	mJ
I <sub>AS</sub>	non-repetitive avalanche current	$V_{sup} \le 50 \text{ V}; V_{GS} = 10 \text{ V}; T_{j(init)} = 25 \text{ °C};$ R <sub>GS</sub> = 50 $\Omega$ ; unclamped	-	35	А





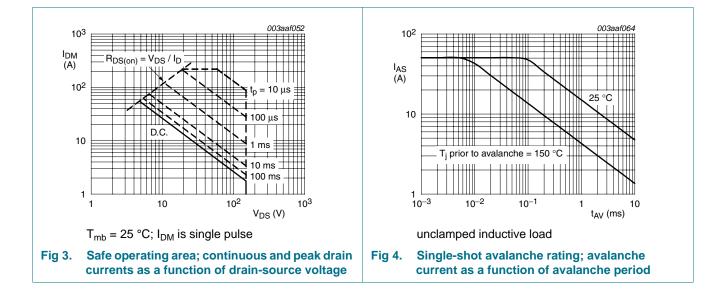


**Product data sheet** 

### Nexperia

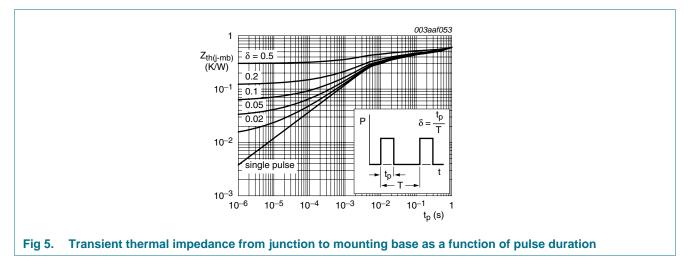
# **PSMN030-150P**

N-channel TrenchMOS SiliconMAX standard level FET



### 5. Thermal characteristics

Parameter	Conditions	Min	Тур	Max	Unit
thermal resistance from junction to mounting base		-	-	0.6	K/W
thermal resistance from junction to ambient	in free air	-	60	-	K/W
	thermal resistance from junction to mounting base	thermal resistance from junction to mounting base	thermal resistance from junction to mounting - base	thermal resistance from junction to mounting base	thermal resistance from junction to mounting 0.6 base



#### Table 5. Thermal characteristics

### 6. Characteristics

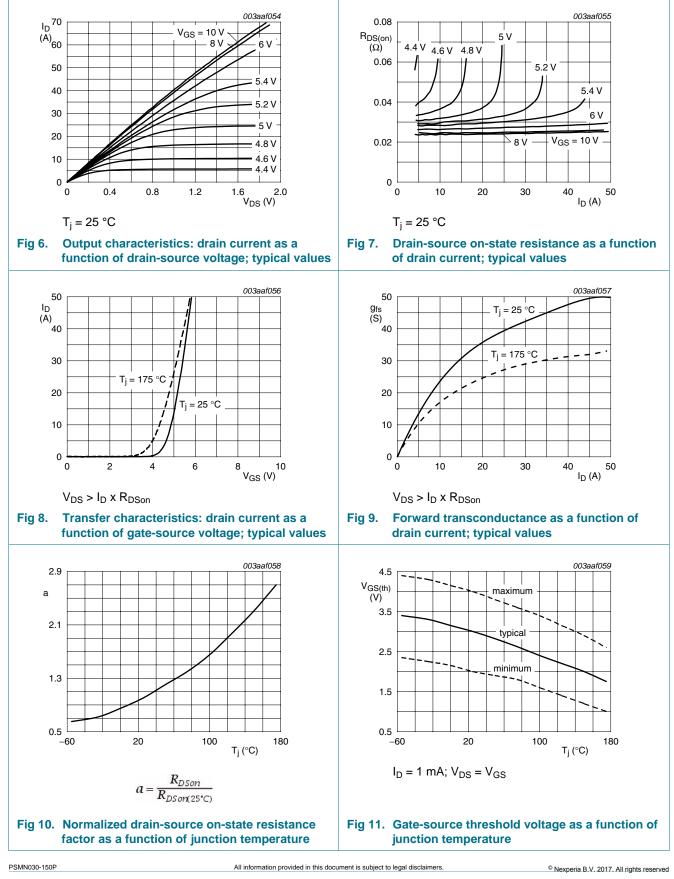
Table 6.	Characteristics					
Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
Static cha	aracteristics					
V <sub>(BR)DSS</sub>		$I_D = 0.25 \text{ mA}; V_{GS} = 0 \text{ V}; T_j = -55 \text{ °C}$	133	-	-	V
	voltage	$I_D$ = 0.25 mA; $V_{GS}$ = 0 V; $T_j$ = 25 °C	150	-	-	V
V <sub>GS(th)</sub>	/ <sub>GS(th)</sub> gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}$	-	-	6	V
		$I_D$ = 1 mA; $V_{DS}$ = $V_{GS}$ ; $T_j$ = 25 °C	2	3	4	V
	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 175 \text{ °C}$	1	-	-	V	
I <sub>DSS</sub>	drain leakage current	$V_{DS} = 150 \text{ V};  V_{GS} = 0 \text{ V};  T_j = 25 ^{\circ}\text{C}$	-	0.05	10	μA
		$V_{DS}$ = 150 V; $V_{GS}$ = 0 V; $T_j$ = 175 $^\circ C$	-	-	500	μA
I <sub>GSS</sub>	gate leakage current	$V_{GS} = 10 \text{ V};  V_{DS} = 0 \text{ V};  T_j = 25 ^{\circ}\text{C}$	-	2	100	nA
		$V_{GS}$ = -10 V; $V_{DS}$ = 0 V; $T_j$ = 25 °C	-	2	100	nA
$R_{DSon}$	drain-source on-state	$V_{GS}$ = 10 V; $I_D$ = 25 A; $T_j$ = 175 °C	-	-	81	mΩ
	resistance	$V_{GS} = 10 \text{ V}; \text{ I}_D = 25 \text{ A}; \text{ T}_j = 25 ^\circ\text{C}$	-	24	30	mΩ
Dynamic	characteristics					
Q <sub>G(tot)</sub>	total gate charge	$I_D = 55.5 \text{ A}; V_{DS} = 120 \text{ V}; V_{GS} = 10 \text{ V}; T_j = 25 \text{ °C}$	-	98	-	nC
$Q_{GS}$	gate-source charge		-	16	-	nC
$Q_{GD}$	gate-drain charge		-	38	50	nC
C <sub>iss</sub>	input capacitance	$V_{DS} = 25 \text{ V}; V_{GS} = 0 \text{ V}; f = 1 \text{ MHz};$	-	3680	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C	-	470	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	220	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 75 \text{ V}; \text{ R}_{L} = 1.5 \Omega; \text{ V}_{GS} = 10 \text{ V};$	-	18	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5.6 \ \Omega; \ T_j = 25 \ ^{\circ}C$	-	71	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	97	-	ns
t <sub>f</sub>	fall time		-	76	-	ns
L <sub>D</sub>	internal drain inductance	measured from tab to centre of die ; $T_j = 25 \ ^{\circ}C$	-	3.5	-	nH
		measured from drain lead to centre of die (SOT78 package only) ; $T_j = 25 \text{ °C}$	-	4.5	-	nH
L <sub>S</sub>	internal source inductance	measured from source lead to source bond pad ; $T_j = 25 \text{ °C}$	-	7.5	-	nH
Source-d	rain diode					
V <sub>SD</sub>	source-drain voltage	$I_{S} = 25 \text{ A}; V_{GS} = 0 \text{ V}; T_{j} = 25 \text{ °C}$	-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_{S} = 20 \text{ A}; \text{ dI}_{S}/\text{dt} = -100 \text{ A}/\mu\text{s};$	-	109	-	ns
Q <sub>r</sub>	recovered charge	$V_{GS} = 0 \text{ V};  V_{DS} = 30 \text{ V};  T_j = 25 ^{\circ}\text{C}$	-	610	-	nC

PSMN030-150P Product data sheet

### Nexperia

# **PSMN030-150P**

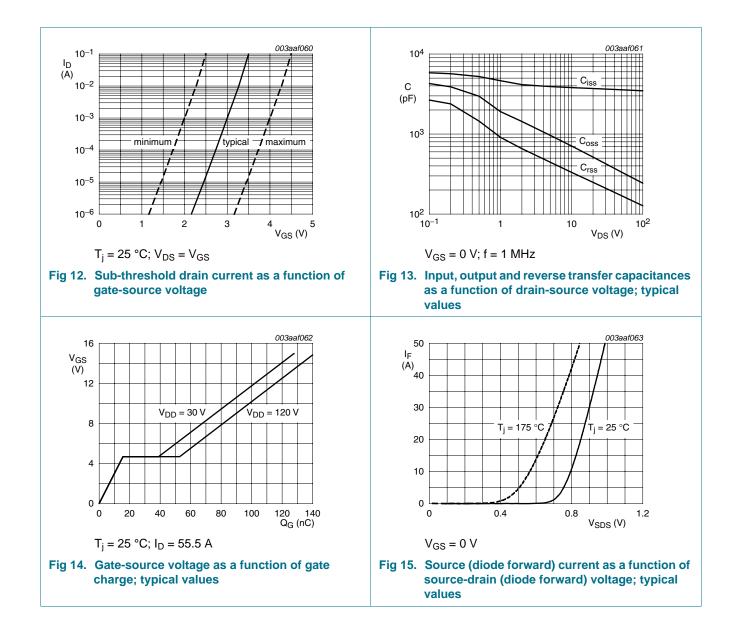
### N-channel TrenchMOS SiliconMAX standard level FET



### Nexperia

# **PSMN030-150P**

### N-channel TrenchMOS SiliconMAX standard level FET



### N-channel TrenchMOS SiliconMAX standard level FET

#### **Package outline** 7.

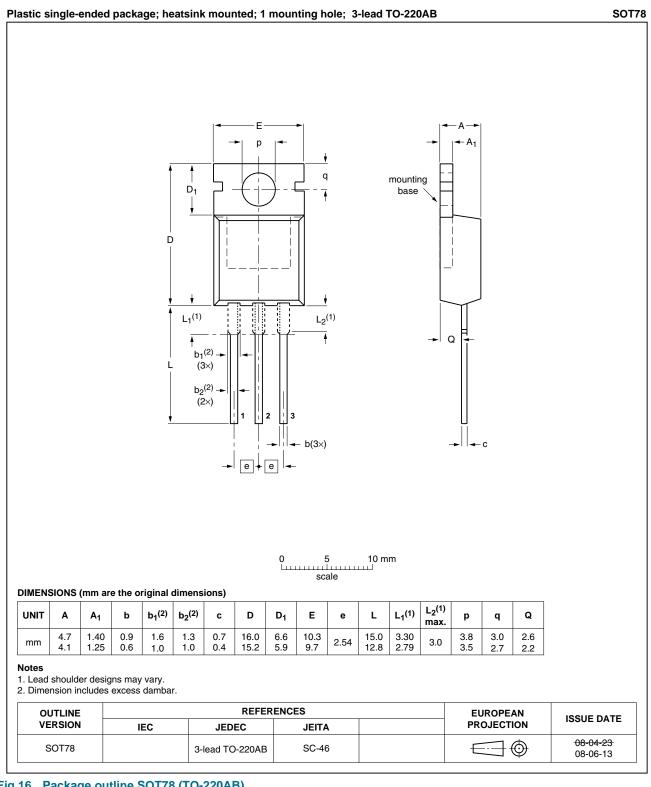


Fig 16. Package outline SOT78 (TO-220AB)

PSMN030-150P **Product data sheet** 

### 8. Revision history

Table 7. Revision h	nistory			
Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN030-150P v.2	20101216	Product data sheet	-	PSMN030-150P v.1
Modifications:	<ul> <li>The format of of NXP Semic</li> </ul>	this data sheet has been rec conductors.	lesigned to comply with	the new identity guidelines
	<ul> <li>Legal texts hat</li> </ul>	ve been adapted to the new	company name where	appropriate.
PSMN030-150P v.1	20000601	Product specification	-	-

### 9. Legal information

### 9.1 Data sheet status

Document status[1][2]	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nexperia.com.

### 9.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. Nexperia does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local Nexperia sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

**Product specification** — The information and data provided in a Product data sheet shall define the specification of the product as agreed between Nexperia and its customer, unless Nexperia and

customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the Nexperia product is deemed to offer functions and qualities beyond those described in the Product data sheet.

### 9.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

In no event shall Nexperia be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, Nexperia's aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of Nexperia.

**Right to make changes** — Nexperia reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof. Suitability for use — Nexperia products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of a Nexperia product can reasonably be expected to result in personal injury, death or severe property or environmental damage. Nexperia accepts no liability for inclusion and/or use of Nexperia products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Quick reference data** — The Quick reference data is an extract of the product data given in the Limiting values and Characteristics sections of this document, and as such is not complete, exhaustive or legally binding.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. Nexperia makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using Nexperia products, and Nexperia accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the Nexperia product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

Nexperia does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using Nexperia products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). Nexperia does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

#### Terms and conditions of commercial sale - Nexperia

products are sold subject to the general terms and conditions of commercial sale, as published at <u>http://www.nexperia.com/profile/terms</u>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective

PSMN030-150P	

### N-channel TrenchMOS SiliconMAX standard level FET

agreement shall apply. Nexperia hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of Nexperia products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

**Export control** — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

**Non-automotive qualified products** — Unless this data sheet expressly states that this specific Nexperia product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. Nexperia accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without Nexperia's warranty of the

### **10. Contact information**

For more information, please visit: http://www.nexperia.com

For sales office addresses, please send an email to: salesaddresses@nexperia.com

product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond Nexperia's specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies Nexperia for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond Nexperia's standard warranty and Nexperia's product specifications.

### 9.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

### N-channel TrenchMOS SiliconMAX standard level FET

### 11. Contents

1	Product profile1
1.1	General description1
1.2	Features and benefits1
1.3	Applications1
1.4	Quick reference data1
2	Pinning information2
3	Ordering information2
4	Limiting values
5	Thermal characteristics5
6	Characteristics6
7	Package outline9
8	Revision history10
9	Legal information11
9.1	Data sheet status11
9.2	Definitions11
9.3	Disclaimers
9.4	Trademarks12
10	Contact information12

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by NXP manufacturer:

Other Similar products are found below :

614233C 648584F MCH3443-TL-E MCH6422-TL-E FW231A-TL-E APT5010JVR NTNS3A92PZT5G IRF100S201 JANTX2N5237 2SK2464-TL-E 2SK3818-DL-E FCA20N60\_F109 FDZ595PZ STD6600NT4G FSS804-TL-E 2SJ277-DL-E 2SK1691-DL-E 2SK2545(Q,T) 405094E 423220D MCH6646-TL-E TPCC8103,L1Q(CM 367-8430-0972-503 VN1206L 424134F 026935X 051075F SBVS138LT1G 614234A 715780A NTNS3166NZT5G 751625C 873612G IRF7380TRHR IPS70R2K0CEAKMA1 RJK60S3DPP-E0#T2 RJK60S5DPK-M0#T0 APT5010JVFR APT12031JFLL APT12040JVR DMN3404LQ-7 NTE6400 JANTX2N6796U JANTX2N6784U JANTXV2N5416U4 SQM110N05-06L-GE3 SIHF35N60E-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI APT1201R6BVFRG